

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1030753	(plurality multi multiple stack stacking stacked stack mount mounting mounted) with (semiconductor chip die dice component ic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:41
L2	590687	(stack stacking stacked stack mount mounting mounted) with (semiconductor chip die dice component ic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:41
L3	63942	(offset extended extending beyond over) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:42
L4	12684	(package packaging packaged) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:42
L5	1217936	wire and "5"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:43
L6	6628	wire and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 21:43
L7	240	(redistributing redistribution redistribute redistributed) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 22:00
L8	2	"6239496".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 22:01